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PATENT

Attorney Reference Number 6047-67518-01
Application Number 10/731,995

Claims

1-40. (canceled)

41. (currently amended) A mold for molding a package for a plurality of die bonded to a substrate, the mold comprising a first mold portion that defines a package cover for encapsulating the plurality of die and a portion of a surface of the substrate to which the die are bonded, and a second mold portion that defines a plurality of ribs having a thickness at least as great as a solder bump thickness and that projects outwardly from a surface of the substrate opposite the surface of the substrate to which the plurality of die are bonded The mold of claim 40, wherein the first mold portion and the second mold portion define package covers and ribs for a plurality of die bonded to the substrate.

42-59. (canceled)